Georgia Tech Laboratory for Smart Structural Systems

http://wang.ce.gatech.edu School of Civil and Environmental Engineering

Passive Wireless Strain Sensing through RFID

[1] Dan Li, [1,2] Yang Wang

[1] School of Civil and Environmental Engineering
[2] School of Electrical and Computer Engineering
Georgia Institute of Technology

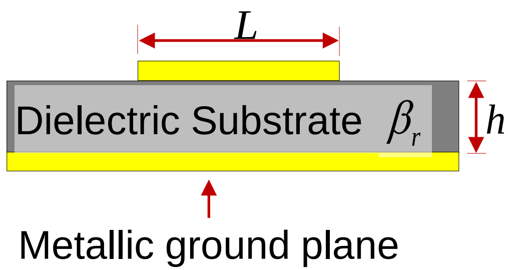
Passive Wireless Sensor Technology (PWST)
WiSEE 2018
December 12, 2018

Outline

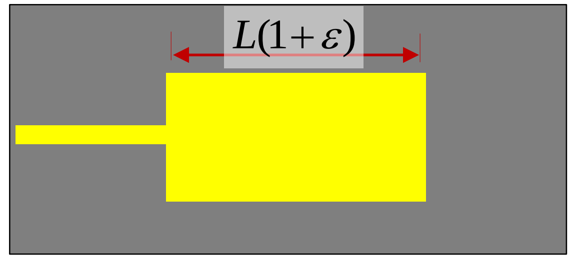
- Research Background & Motivation
- Thermal Stability Tests
- Material Property Tests
  - Constitutive Relationship of Substrate
  - Constitutive Relationship of Glue
  - Dielectric Constant of Substrate
- Multi-Physics Simulation
- Validation Tests
  - Strain Sensing Test
  - Crack Sensing Test
- Conclusion

Strain Sensing Mechanism

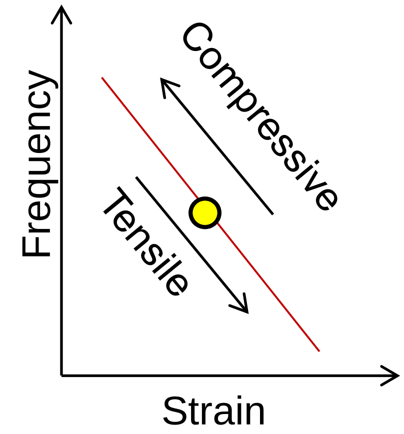
Patch Antenna



Side View



Top View



Electromagnetic resonance frequency of a patch antenna (at zero strain):

$$f_{\mathrm{R0}} \approx \frac{c}{2L\sqrt{\beta_{\mathrm{r}}}}$$

c -- speed of light

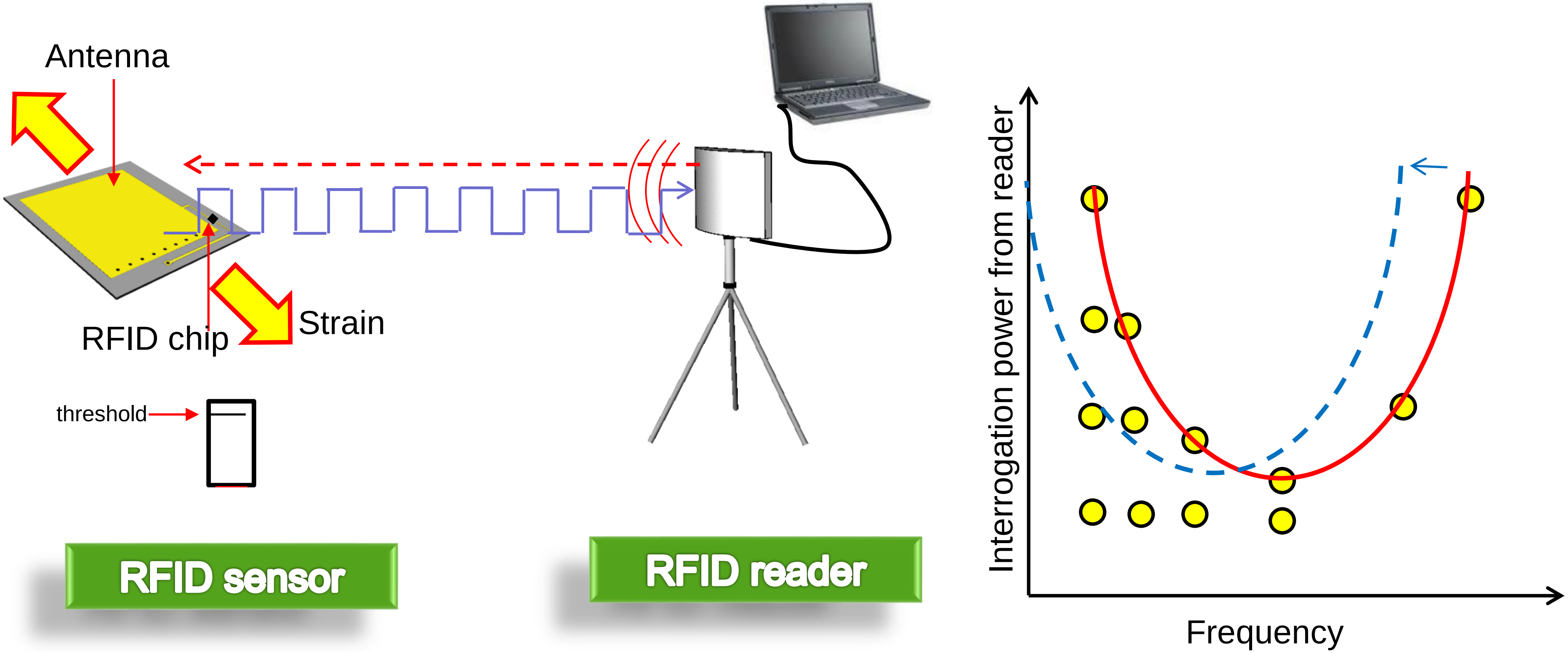
L -- length of microstrip patch antenna (half wavelength)

β_{r} -- effective dielectric constant of the antenna substrate

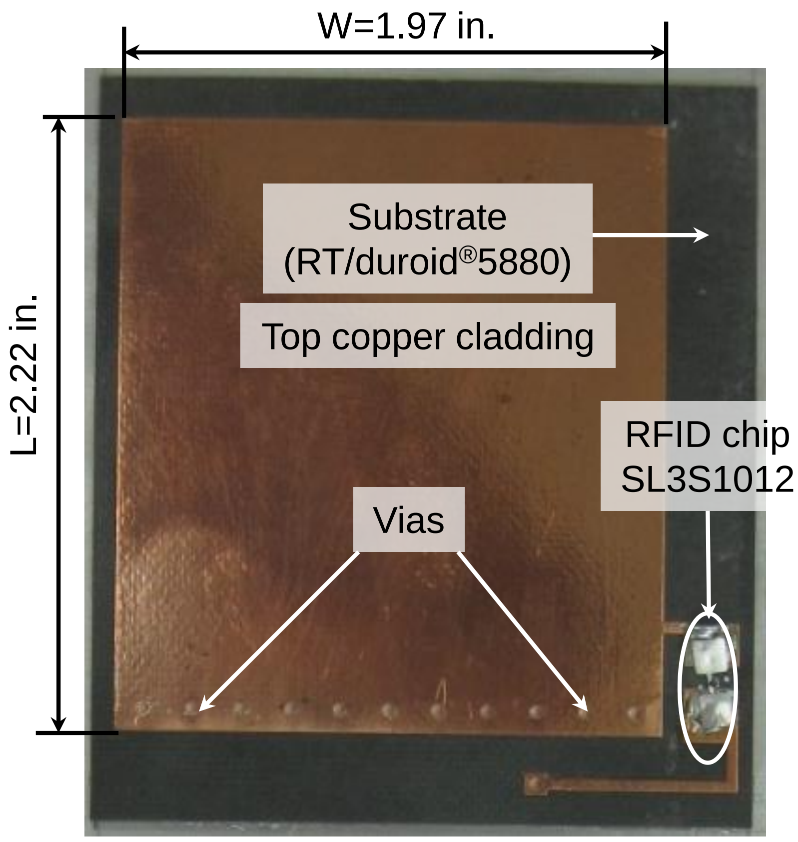
Under strain ε, resonance frequency shifts to $f_{\mathrm{R}} \approx \dfrac{c}{2(1+\varepsilon)L\sqrt{\beta_{\mathrm{r}}}} = \dfrac{f_{\mathrm{R0}}}{1+\varepsilon} \approx f_{\mathrm{R0}}(1-\varepsilon)$

Strain sensitivity is $S = \dfrac{f_{\mathrm{R}} - f_{\mathrm{R0}}}{\varepsilon}$ (Hz/με)

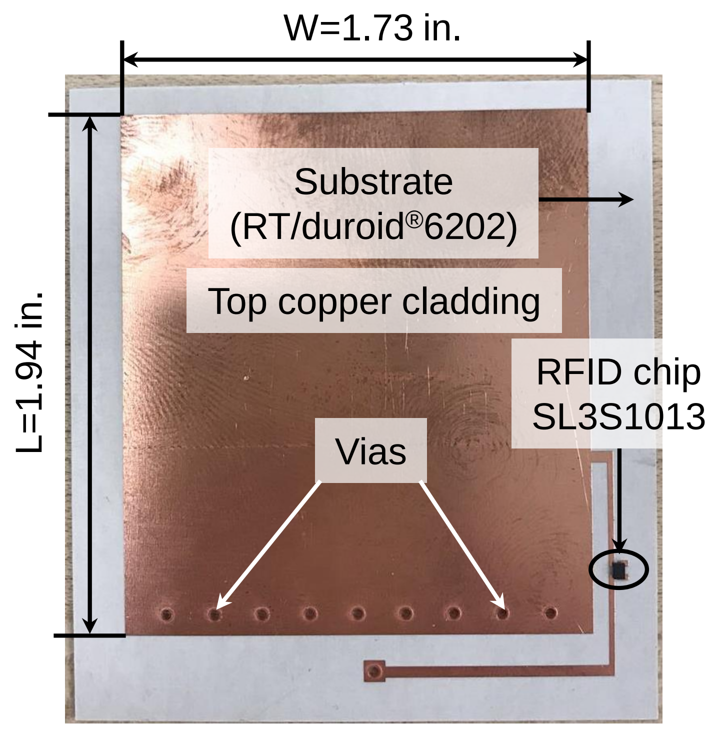
RFID Reader-Sensor System



Antenna Sensor Design



Old Design

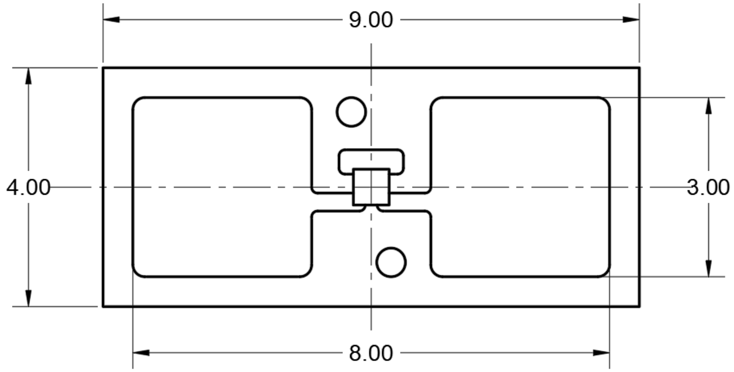


New Design

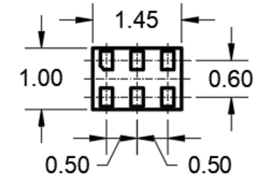
Difference from Previous Design

- **Chip**

Old chip: SL3S1002 (Unit: mm)



New chip: SL3S1013 (Unit: mm)



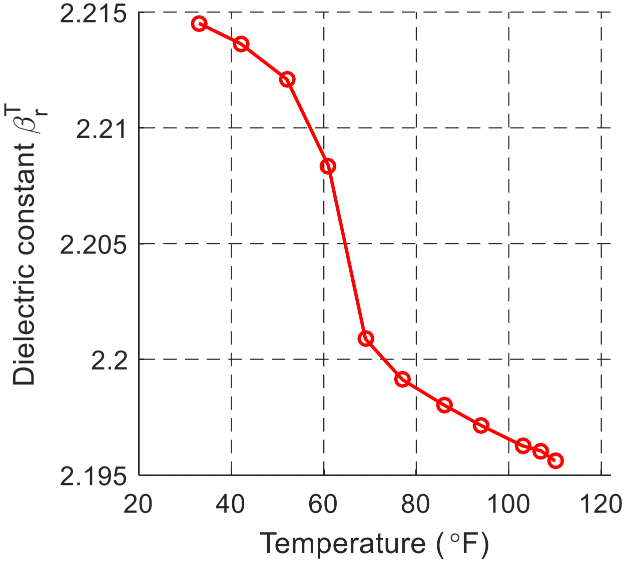
Impedance: 13.3-j122 Ω

Impedance: 21.2-j199.7 Ω

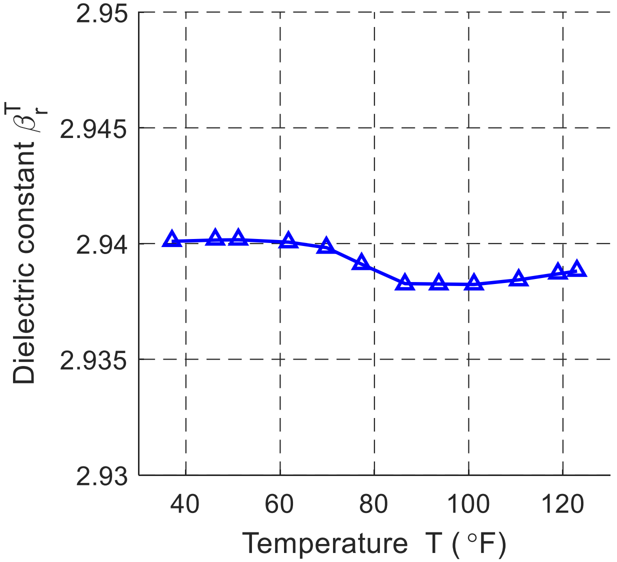
- **Substrate dielectric constant β_r**

$$f_{R0} \approx \frac{c}{2L\sqrt{\beta_r}}$$

RT/duroid® 5880



RT/duroid® 6202



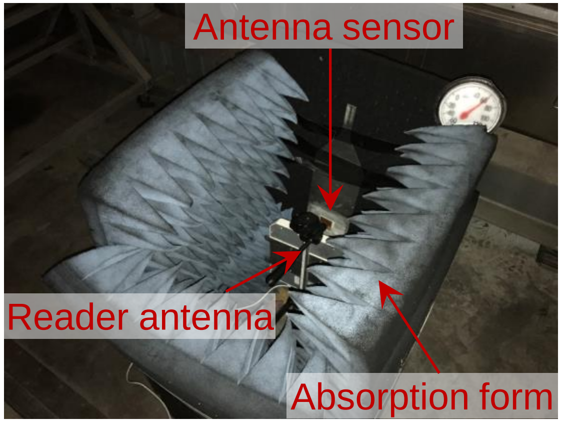
Outline

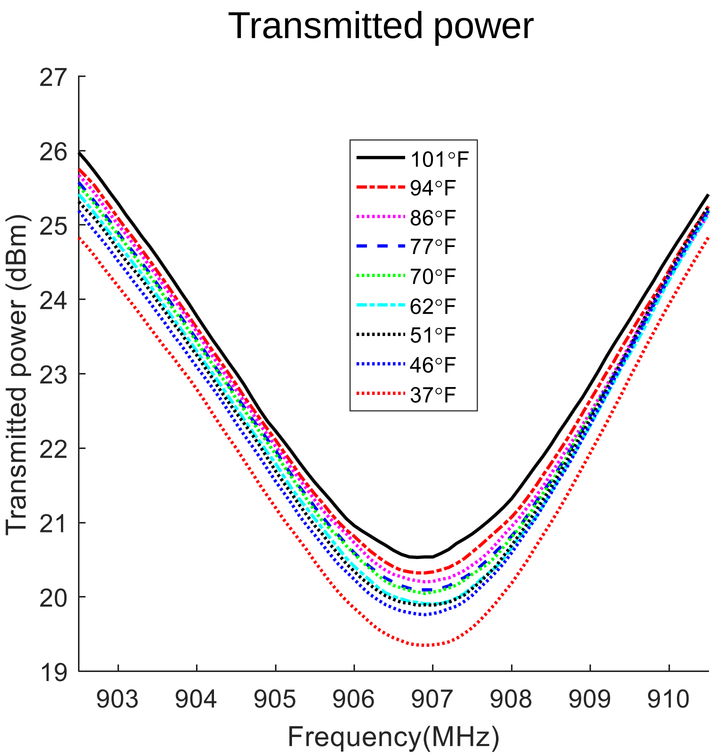
- Research Background & Motivation
- Thermal Stability Tests
- Material Property Tests
  - Constitutive Relationship of Substrate
  - Constitutive Relationship of Glue
  - Dielectric Constant of Substrate
- Multi-Physics Simulation
- Validation Tests
  - Strain Sensing Test
  - Crack Sensing Test
- Conclusion

Temperature Chamber Test

- Thermal influence on the new substrate material RT/duroid® 6202 is investigated through a temperature chamber experiment.
- At each temperature step, sweep frequency band 902.5 ~ 910.5 MHz.
- From transmitted power curve, resonance frequency is extracted.
- RT/duroid® 6202 is thermally stable on dielectric constant.

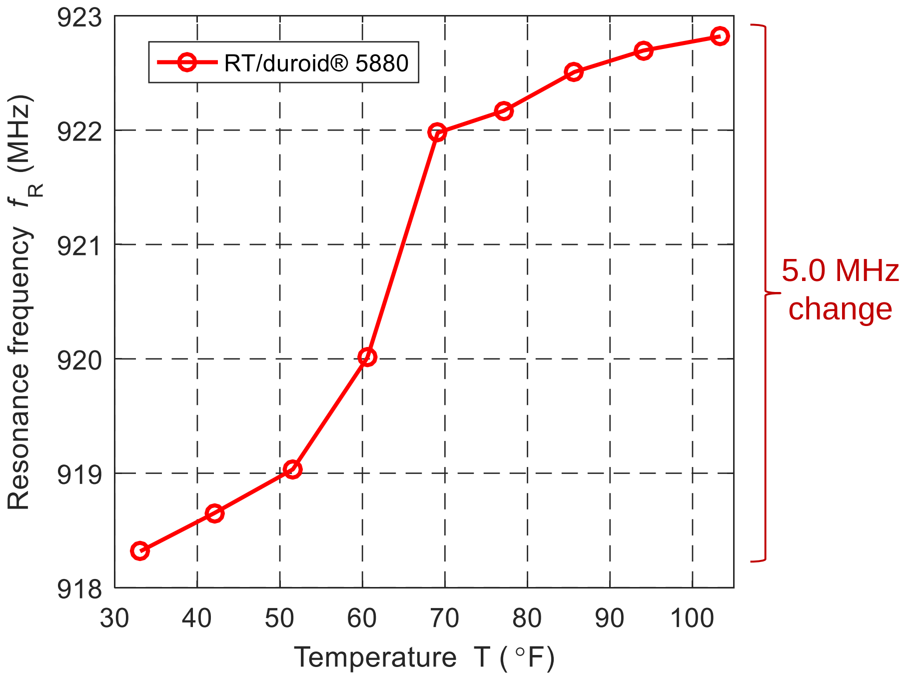
Experiment setup





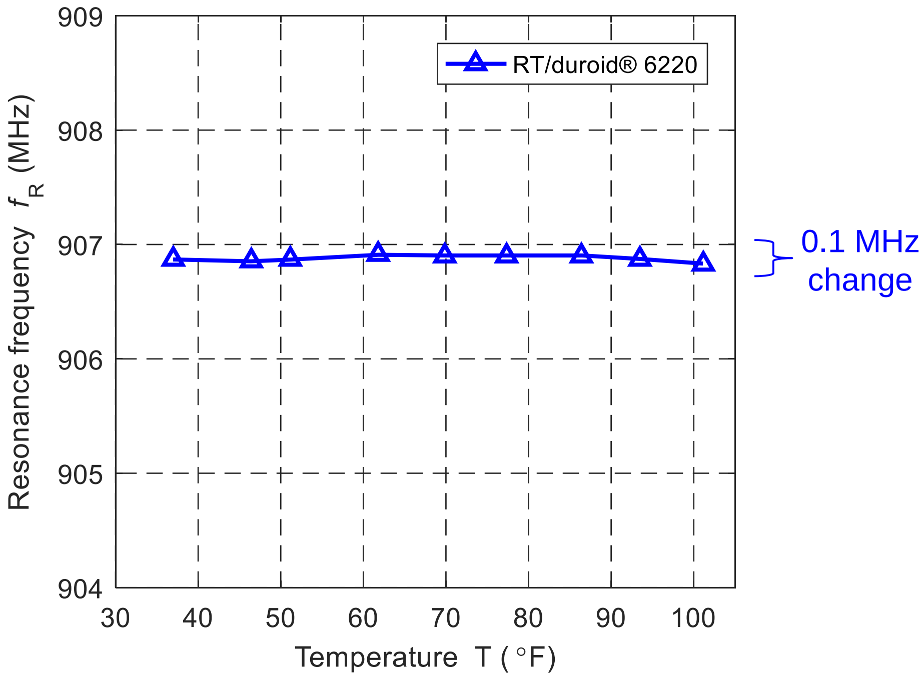
Comparison with RT/duroid® 5880

RT/duroid® 5880



Dielectric constant changes significantly due to temperature fluctuation.

RT/duroid® 6202



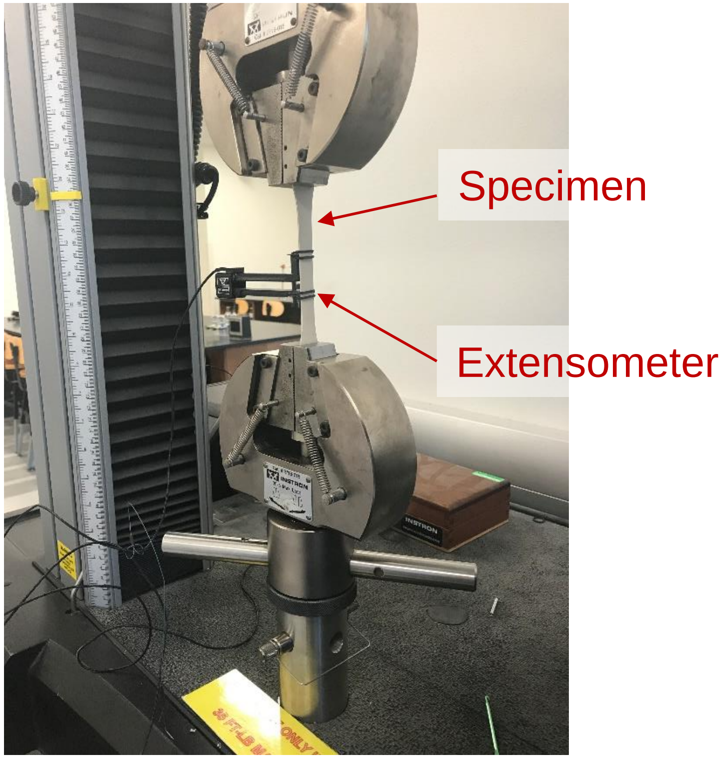
Dielectric constant is more stable to temperature fluctuation.

Outline

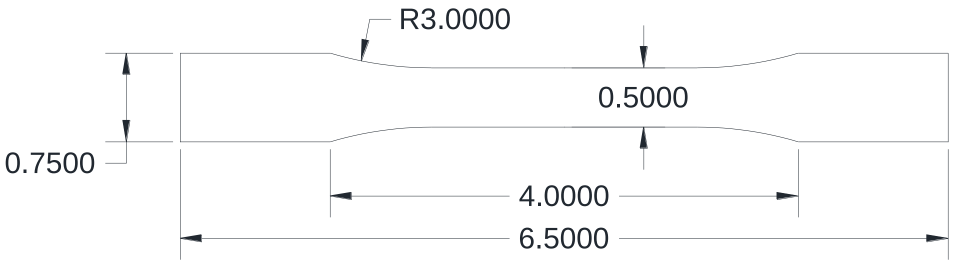
- ❑ Research Background & Motivation
- ❑ Thermal Stability Tests
- ❑ Material Property Tests
  - ➢ Constitutive Relationship of Substrate
  - ➢ Constitutive Relationship of Glue
  - ➢ Dielectric Constant of Substrate
- ❑ Multi-Physics Simulation
- ❑ Validation Tests
  - ➢ Strain Sensing Test
  - ➢ Crack Sensing Test
- ❑ Conclusion

Mechanical Property Test

Experiment setup

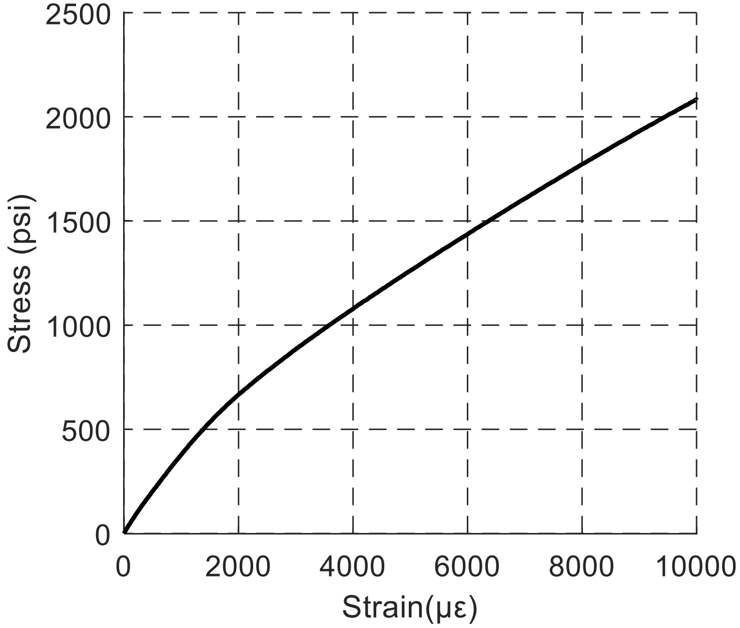


Specimen dimension



Unit: in

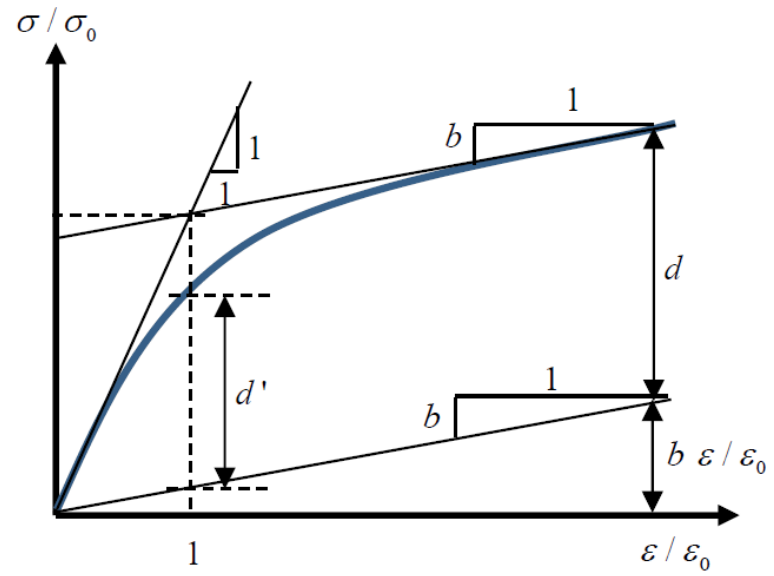
Strain-stress relationship



Menegotto-Pinto Model

Menegotto-Pinto model

$$\frac{\sigma(\varepsilon)}{\sigma_0} = b\frac{\varepsilon}{\varepsilon_0} + \frac{(1-b)\frac{\varepsilon}{\varepsilon_0}}{\left[1+\left(\frac{\varepsilon}{\varepsilon_0}\right)^n\right]^{\frac{1}{n}}}$$



Update parameters: $b, n, \sigma_0, \varepsilon_0$

b : Final tangent stiffness

n : Nonlinear factor

ε_0 : Normalized strain

σ_0 : Normalized stress

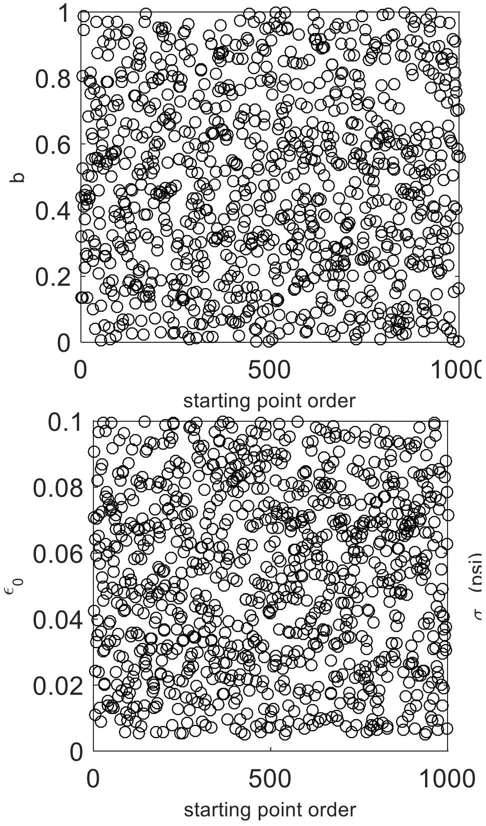
Updated Property Along Longitudinal Direction

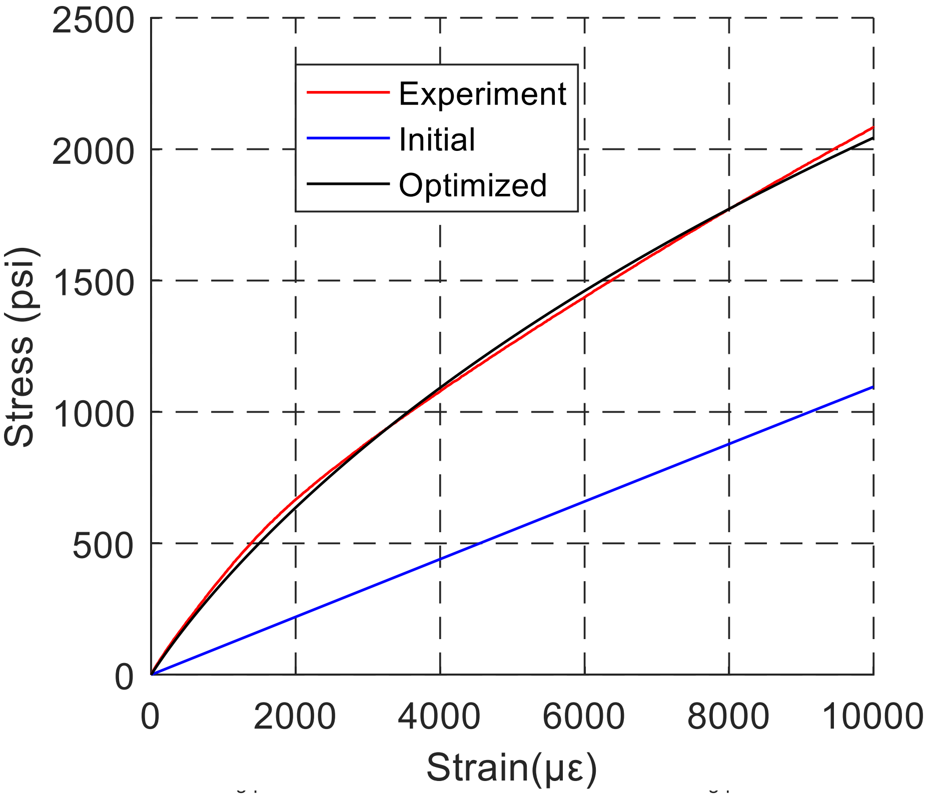
$\mathbf{x_0} = [b, n, \varepsilon_0, \sigma_0] = [0.5, 2.5, 0.05, 5500]$ (one example)

$\mathbf{x_L} = [b, n, \varepsilon_0, \sigma_0] = [0, 0.0001, 0.005, 1000]$ $\quad \mathbf{x_U} = [b, n, \varepsilon_0, \sigma_0] = [1, 5, 0.1, 10000]$

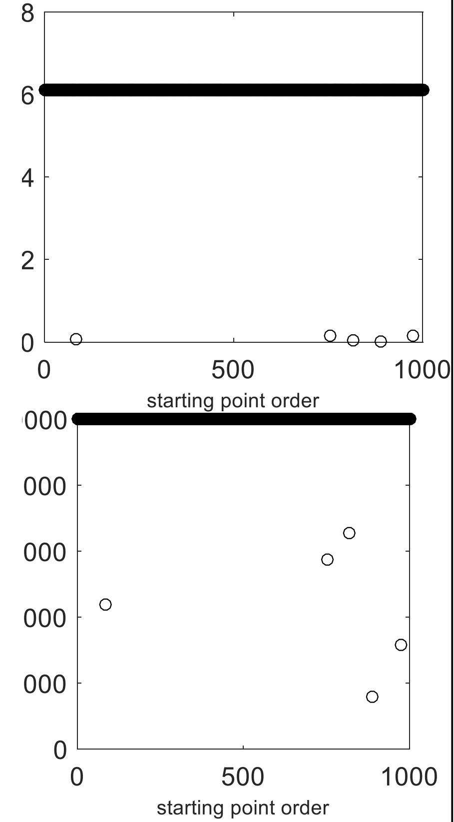
$\mathbf{x}^* = [b, n, \varepsilon_0, \sigma_0] = [2 \times 10^{-14}, 0.61, 0.02, 10000]$

Starting points (1000) are generated





Optimized parameters



Updated Property Along Transverse Direction

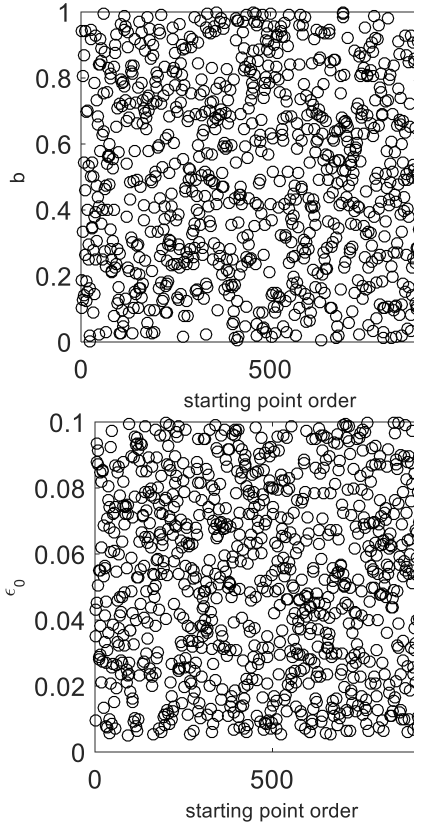
$\mathbf{x_0} = [b, n, \varepsilon_0, \sigma_0] = [0.5, 2.5, 0.05, 5500]$ (one example)

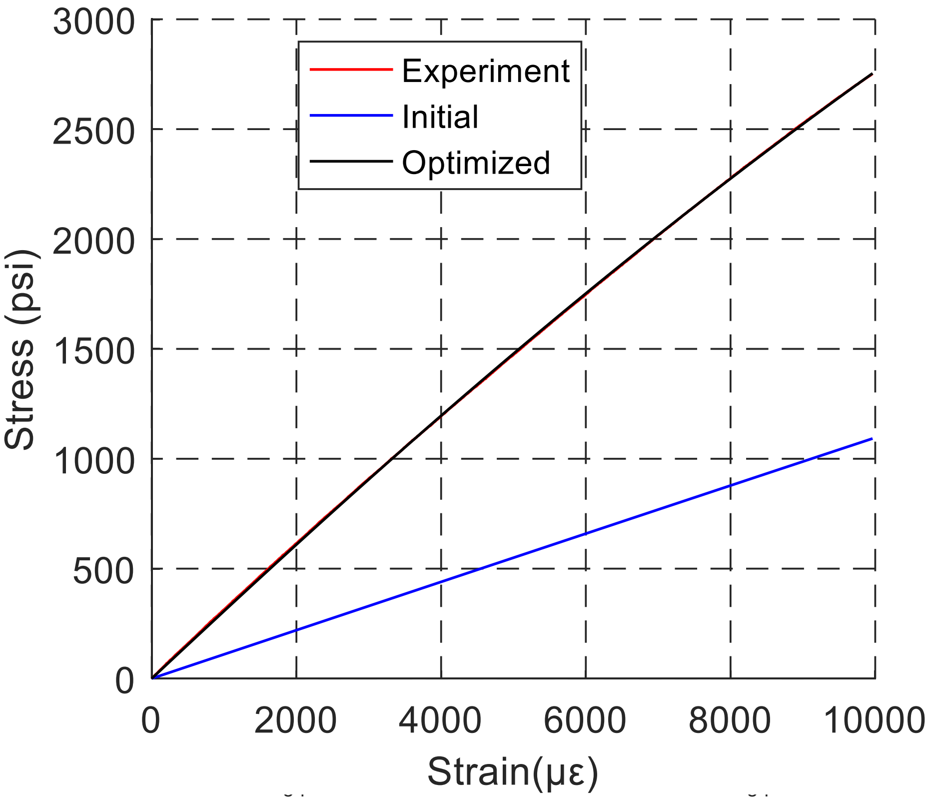
$\mathbf{x_L} = [b, n, \varepsilon_0, \sigma_0] = [0, 0.0001, 0.005, 1000]$ $\mathbf{x_U} = [b, n, \varepsilon_0, \sigma_0] = [1, 5, 0.1, 10000]$

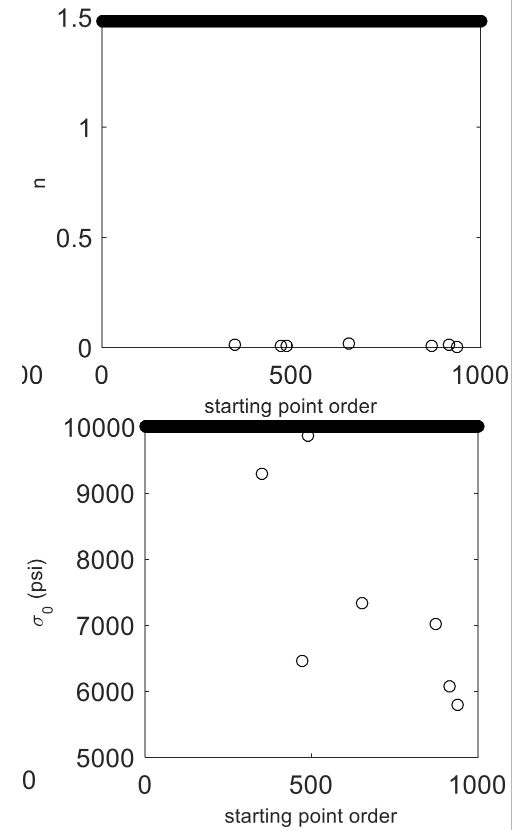
$\mathbf{x}^* = [b, n, \varepsilon_0, \sigma_0] = [2 \times 10^{-14}, 1.48, 0.03, 10000]$

Starting points (1000) are generated

Optimized parameters



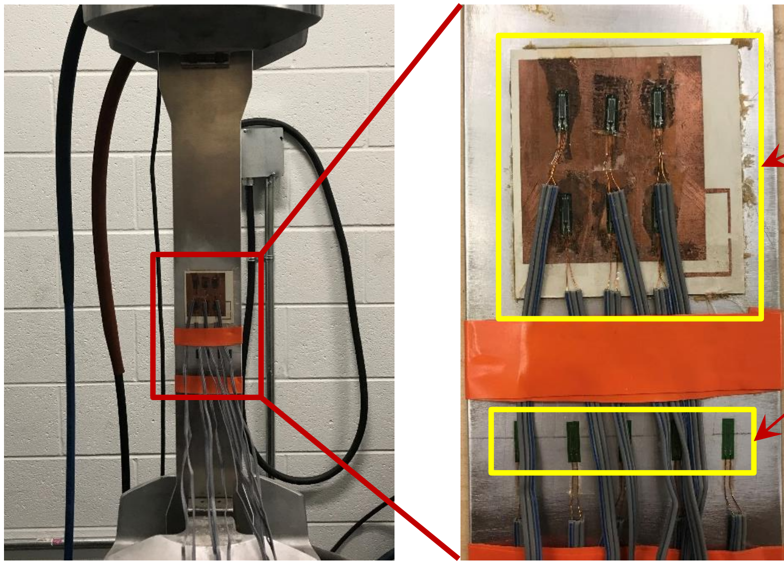




Outline

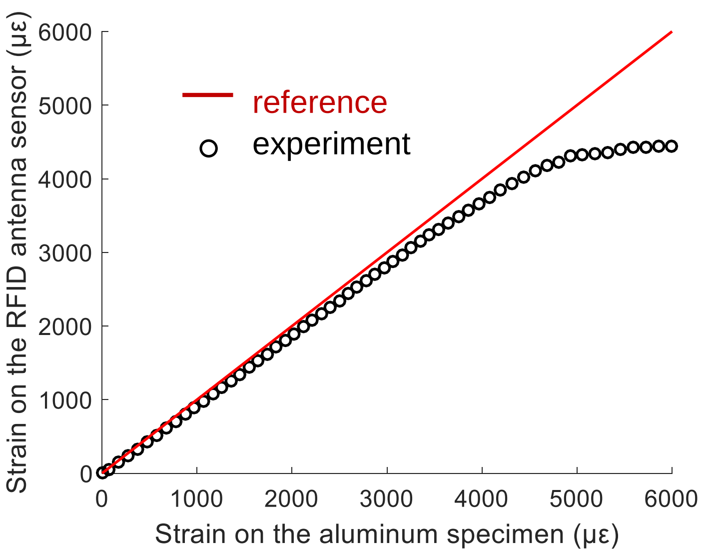
- Research Background & Motivation
- Thermal Stability Tests
- Material Property Tests
  - Constitutive Relationship of Substrate
  - Constitutive Relationship of Glue
  - Dielectric Constant of Substrate
- Multi-Physics Simulation
- Validation Tests
  - Strain Sensing Test
  - Crack Sensing Test
- Conclusion

Strain Transfer Ratio Test

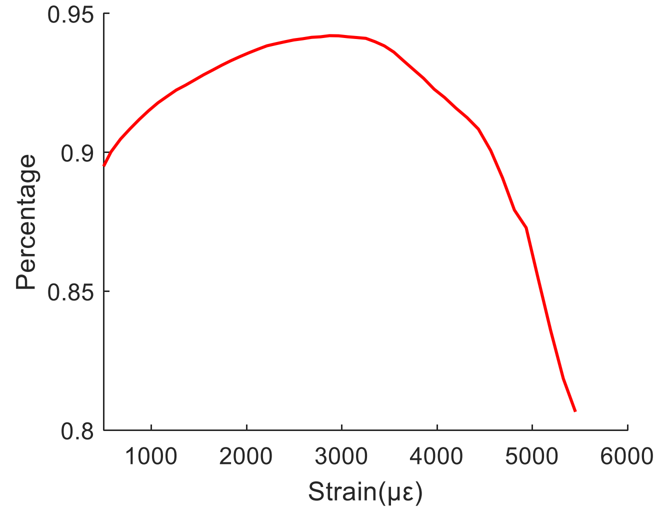


Six strain gages (#1 ~ #6) are installed on top of an RFID patch antenna sensor.

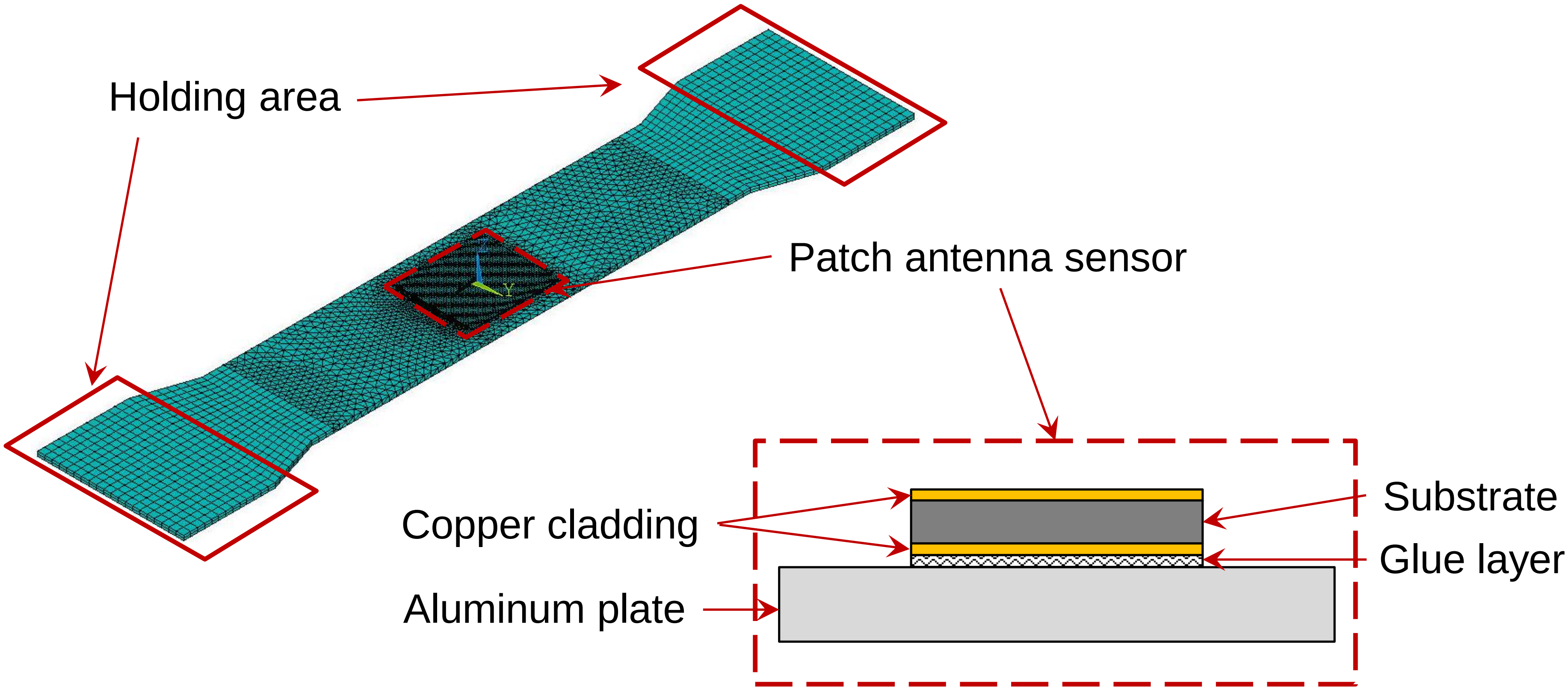
Five traditional strain gages (#7 ~ #11) are installed near the center of the aluminum tensile specimen.



Strain ratio between antenna sensor and aluminum specimen



Strain Transfer Ratio Simulation



- Nonlinear constitutive relationships are used for aluminum, copper, and substrate. (The constitutive relationships are measured by tensile tests.)

Model Updating for Adhesive

- Menegotto-Pinto model with parameters $(b, n, \varepsilon_0, \sigma_0)$ is adopted for nonlinear constitutive model of adhesive.
- Update the parameters $\mathbf{x} = [b, n, \varepsilon_0, \sigma_0]$ by minimizing the difference between experimental strain transfer ratios and simulated strain transfer ratios.

$$\min_{\mathbf{x}} \sum_{i=1}^{m} \left[T_{\mathrm{Exp}}(\varepsilon_i) - T_{\mathrm{Sim}}(\varepsilon_i, \mathbf{x})\right]^2$$

$$\mathrm{s.t.} \quad \mathbf{x}_{\mathrm{L}} \leq \mathbf{x} \leq \mathbf{x}_{\mathrm{U}}$$

where m : the number of strain steps

ε_i : strain level at *i*-th step

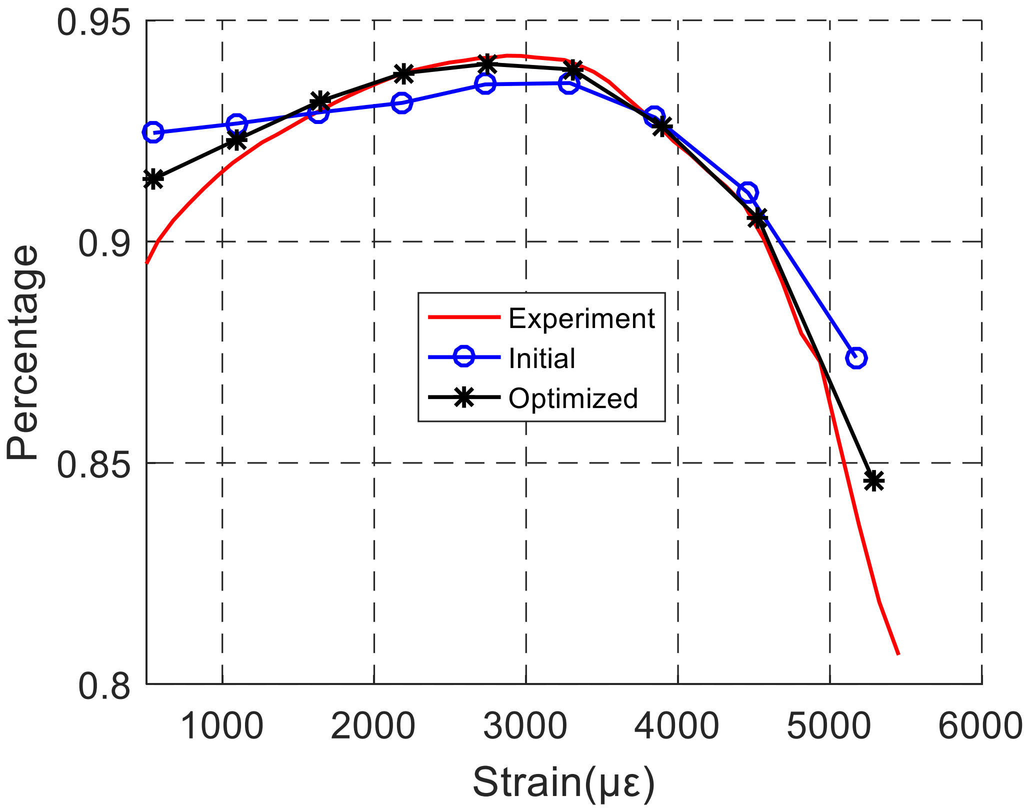
T_{Exp} : strain transfer ratio at ε_i from the experiment

T_{Sim} : strain transfer ratio at ε_i from the simulation

- The optimization problem is solved by Covariance Matrix Adaptation Evolution Strategy (CMA-ES) algorithm.

Hansen, N. (2006), "The CMA evolution strategy: a comparing review", *Towards a new evolutionary computation. Advances on estimation of distribution algorithms*, Springer, pp. 1769–1776.

Model Updating Result



After model updating on adhesive, the simulated strain transfer ratio is closer to the experimental strain transfer ratio.

Outline

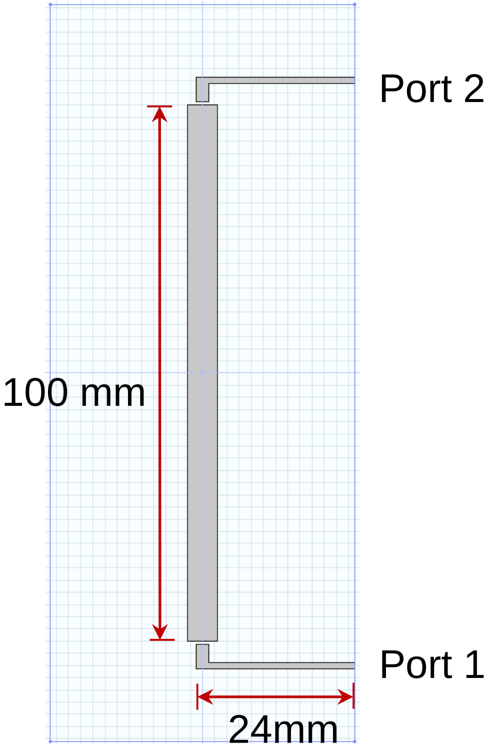
- Research Background & Motivation
- Thermal Stability Tests
- Material Property Tests
  - Constitutive Relationship of Substrate
  - Constitutive Relationship of Glue
  - Dielectric Constant of Substrate
- Multi-Physics Simulation
- Validation Tests
  - Strain Sensing Test
  - Crack Sensing Test
- Conclusion

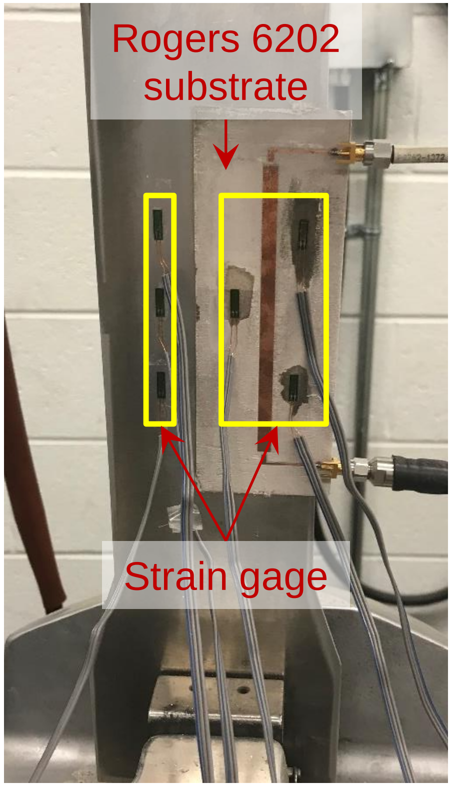
Transmission Line Test

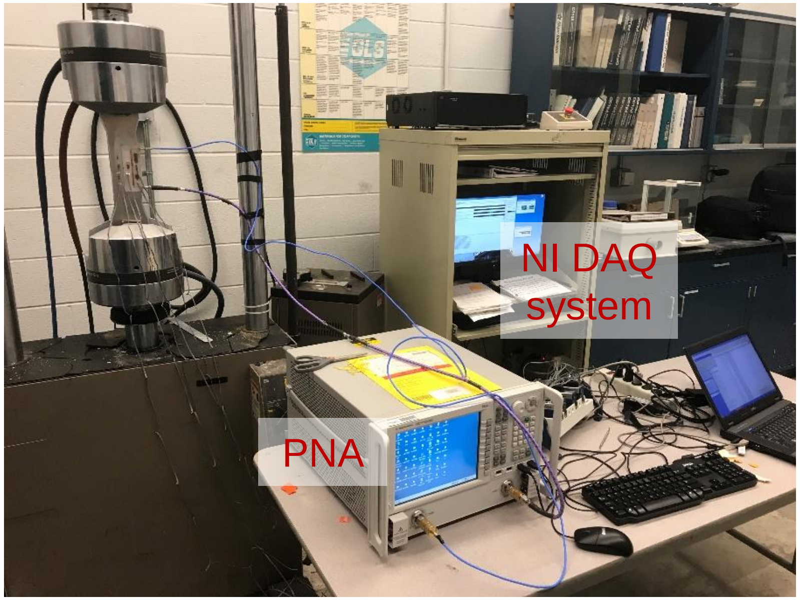
Measure $S_{21}(f) = \dfrac{V_2^{\text{out}}(f)}{V_1^{\text{in}}(f)}$ to update dielectric constant

Specimen

Experiment setup



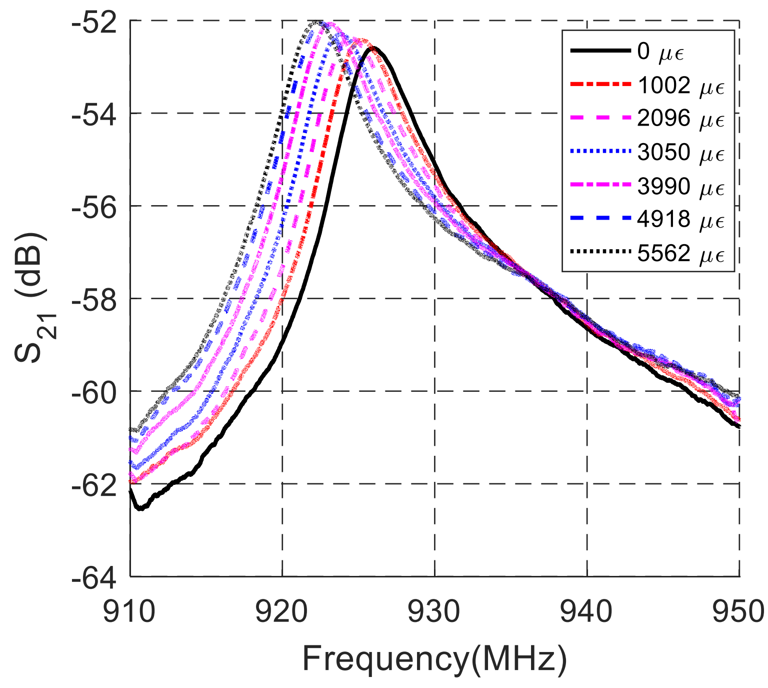




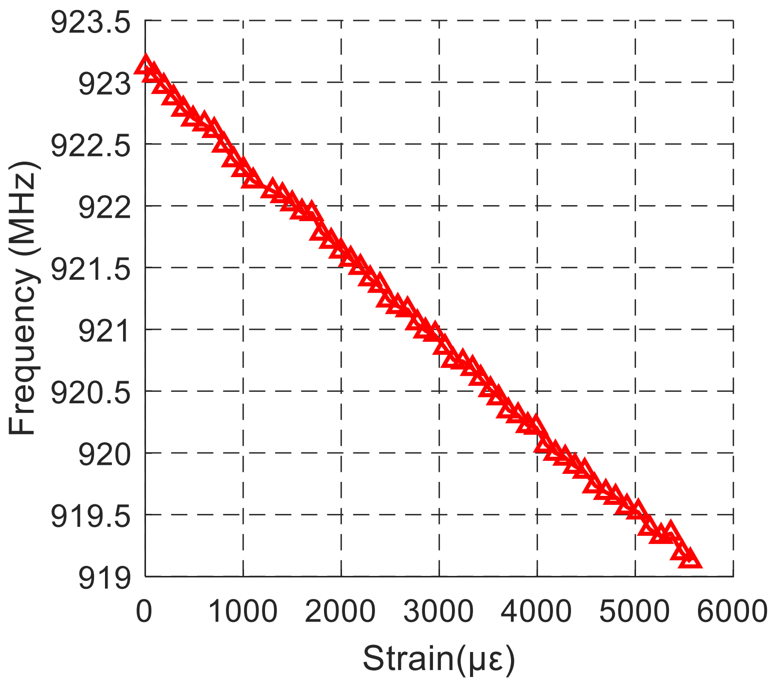
Transmission Line Test Results

- At each temperature step, sweep frequency band 910 ~ 950 MHz
- From S_{21} curve, resonance frequency is extracted

S_{21} curve



Resonance frequency at different strain level



Dielectric Constant Modelling

$$\beta = \beta_0 + \alpha_1 \varepsilon + \alpha_2 \varepsilon (1 - 2\upsilon)$$

where β_0 : dielectric constant value at zero strain

ε : strain level

υ : Poisson's ratio of the substrate

α_1 and α_2 : updating parameters

Update the parameters $\boldsymbol{\alpha} = [\alpha_1, \alpha_2]$ by minimizing the difference between experimental resonance frequencies and calculated resonance frequencies.

$$\min_{\boldsymbol{\alpha}} \sum_{i=1}^{m} \left[f_{\mathrm{Exp}}(\varepsilon_i) - f_{\mathrm{Cal}}(\varepsilon_i, \boldsymbol{\alpha}) \right]^2$$

$$\mathrm{s.t.} \quad \boldsymbol{\alpha}_{\mathrm{L}} \leq \boldsymbol{\alpha} \leq \boldsymbol{\alpha}_{\mathrm{U}}$$

where m : the number of strain steps

ε_i : strain level at *i*-th step

f_{Exp} : resonance frequency at ε_i from the experiment

f_{Cal} : resonance frequency at ε_i from the calculation

Updated Parameters For Dielectric Constant

$$\boldsymbol{\alpha}_0 = [\alpha_1, \alpha_2] = [-0.6, -1]$$

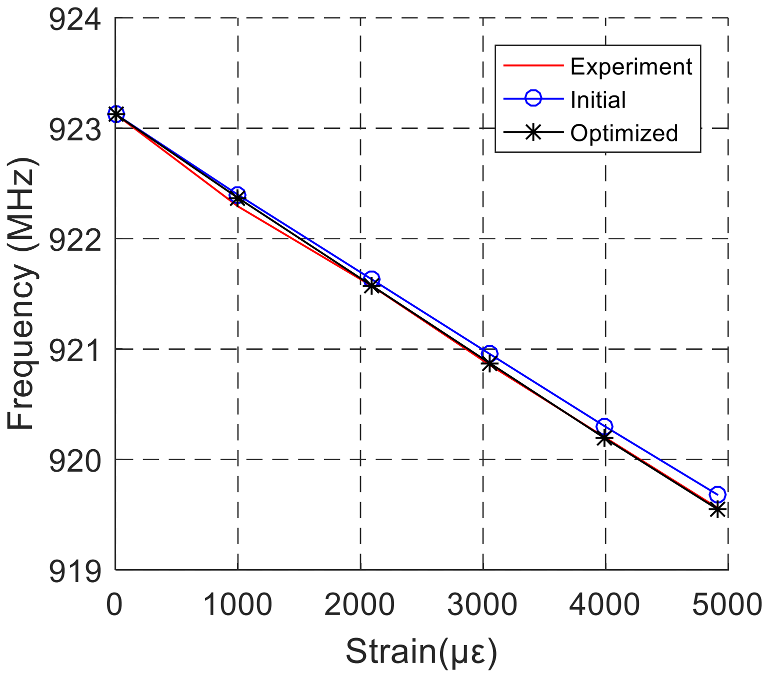
$$\boldsymbol{\alpha}_\mathrm{L} = [\alpha_1, \alpha_2] = [-1, -2.5]$$

$$\boldsymbol{\alpha}_\mathrm{U} = [\alpha_1, \alpha_2] = [-0.2, -0.5]$$

$$\boldsymbol{\alpha}^* = [\alpha_1, \alpha_2] = [-0.2913, -1.5748]$$

The strain effect on dielectric constant

$$\beta = \beta_0 - 0.2913\varepsilon - 1.5748\varepsilon(1 - 2\upsilon)$$

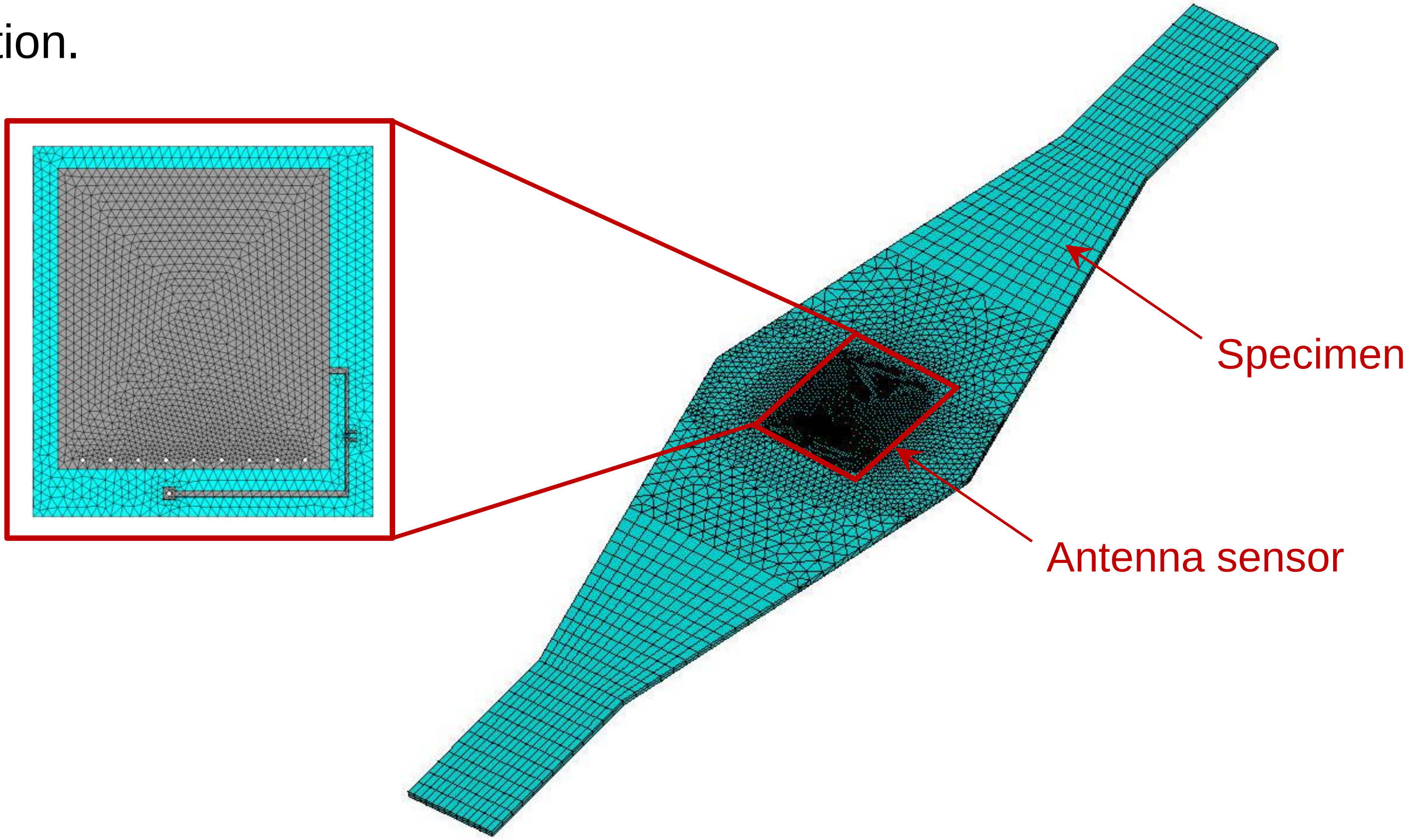


Outline

- Research Background & Motivation
- Thermal Stability Tests
- Material Property Tests
  - Constitutive Relationship of Substrate
  - Constitutive Relationship of Glue
  - Dielectric Constant of Substrate
- **Multi-Physics Simulation**
- Validation Tests
  - Strain Sensing Test
  - Crack Sensing Test
- Conclusion

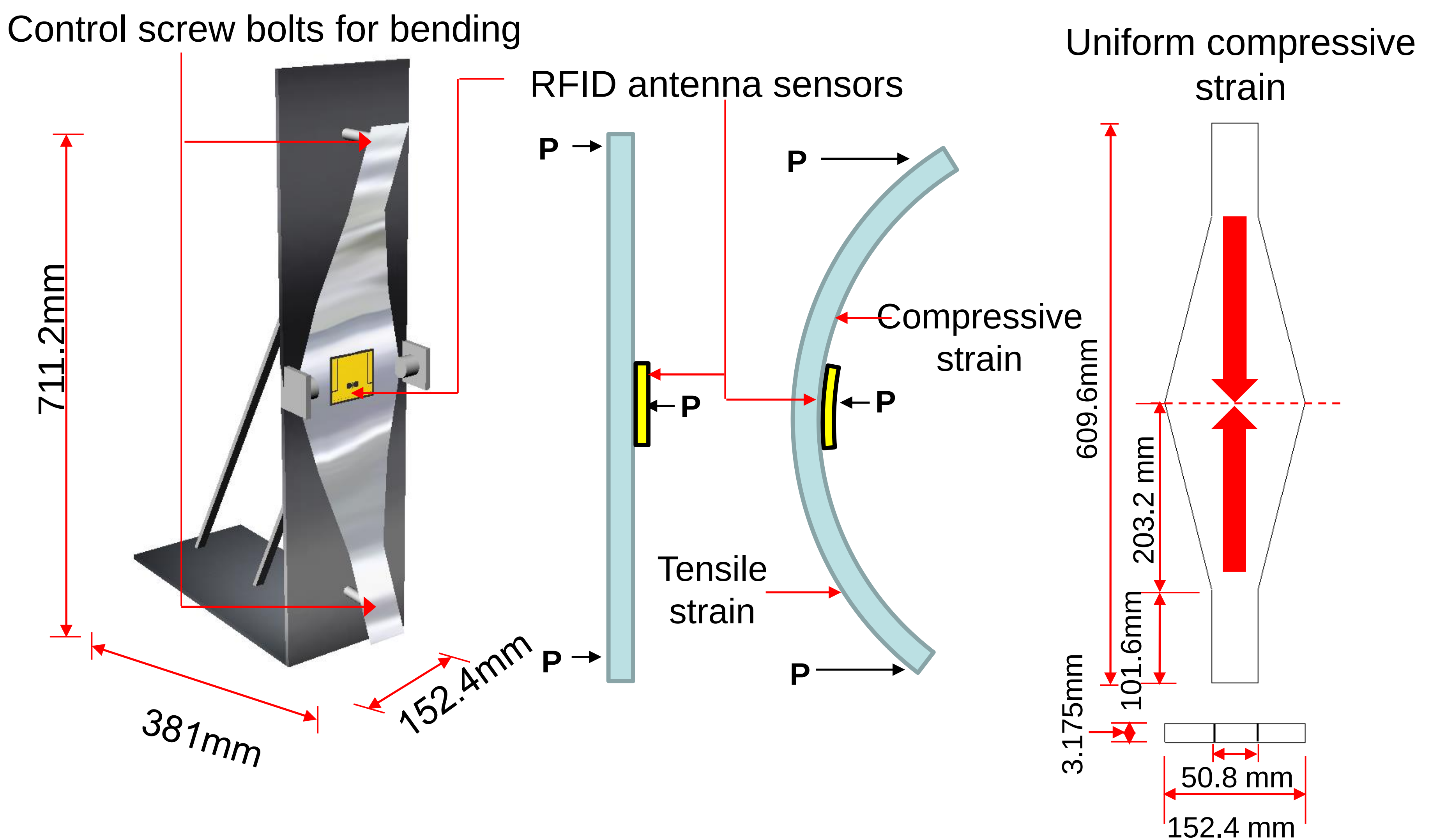
Multi-physics Simulation

- Mechanical simulation with linear constitutive properties and updated nonlinear constitutive properties is conducted.
- Dielectric constant change with strain is considered in the electromagnetic simulation.



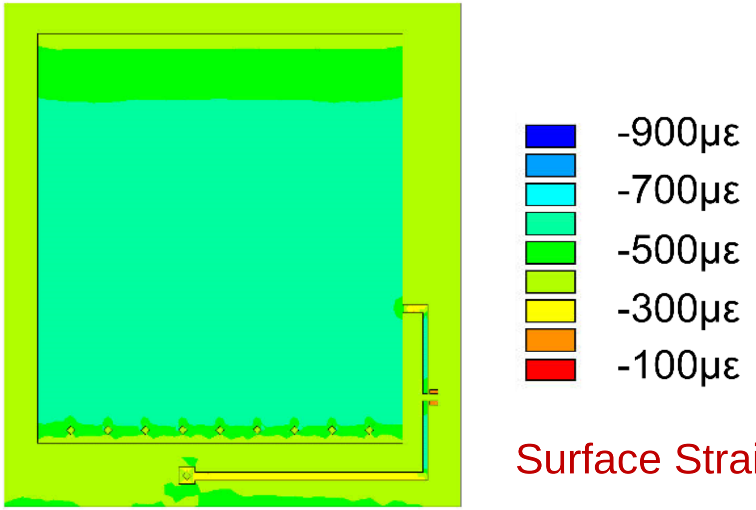
Finite element model

Three-point Bending Setup and Specimen Design

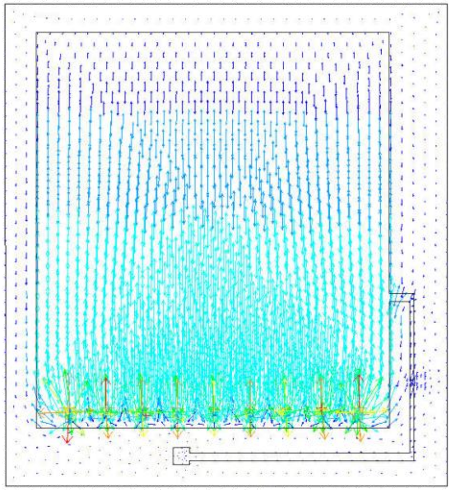


Simulation Results

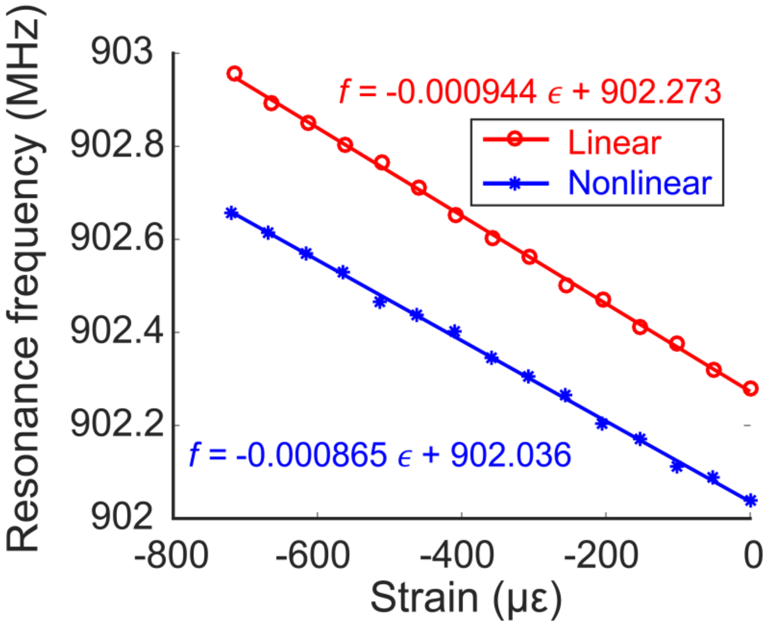
- The relationship between average strain and resonance frequency is investigated.
- Strain sensitivity is calculated as –944 Hz/με using linear constitutive properties, and –865 Hz/με using nonlinear constitutive properties.



Surface Strain



Surface Current



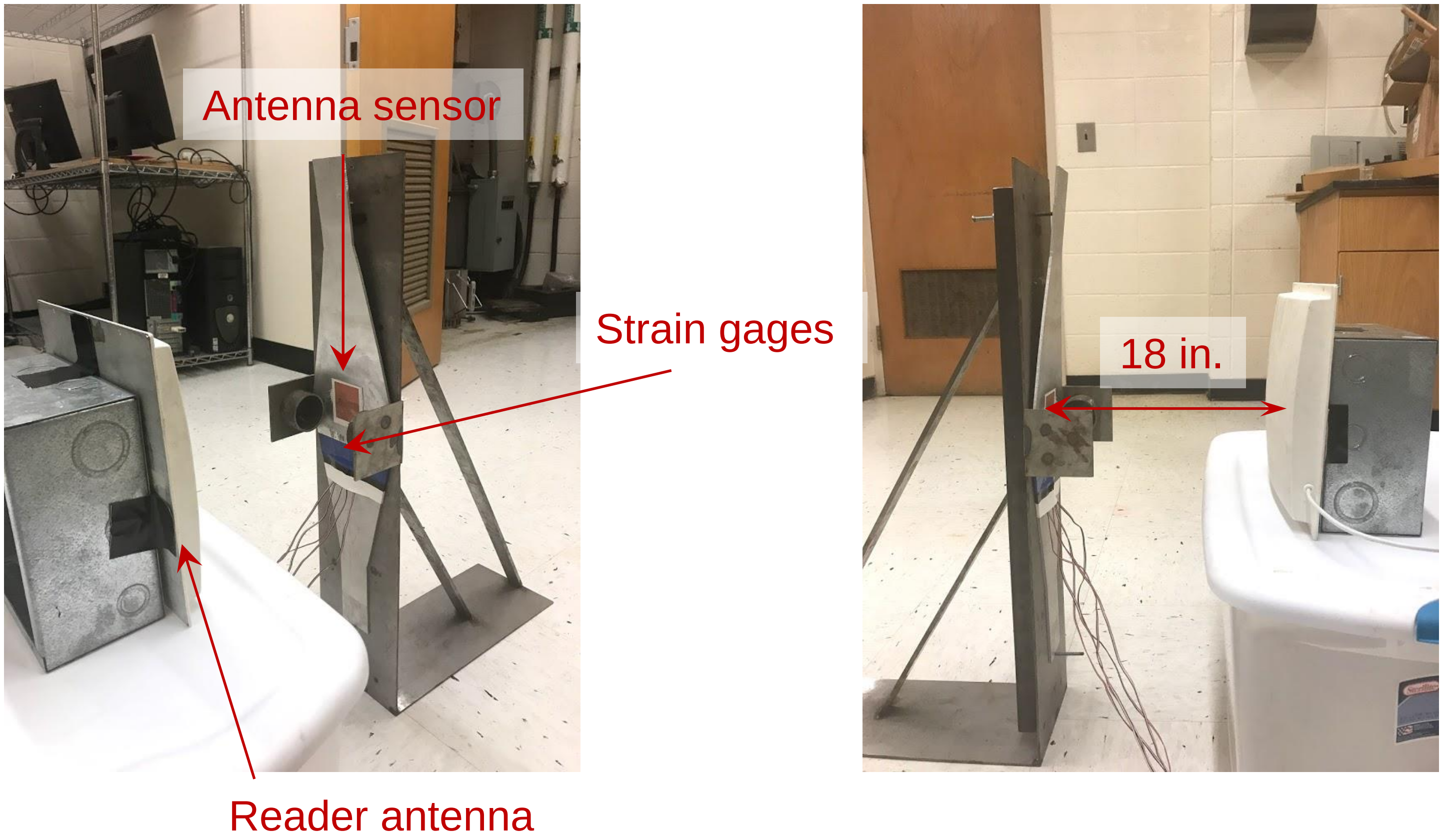
Resonance Frequency Change

Outline

- Research Background & Motivation
- Thermal Stability Tests
- Material Property Tests
  - Constitutive Relationship of Substrate
  - Constitutive Relationship of Glue
  - Dielectric Constant of Substrate
- Multi-Physics Simulation
- Validation Tests
  - Strain Sensing Test
  - Crack Sensing Test
- Conclusion

Compression Test

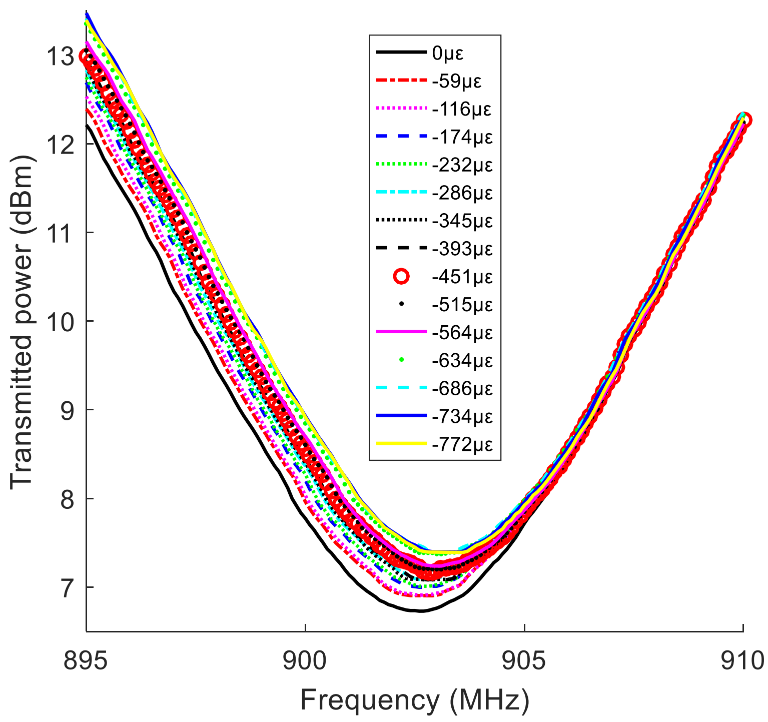
Experiment setup



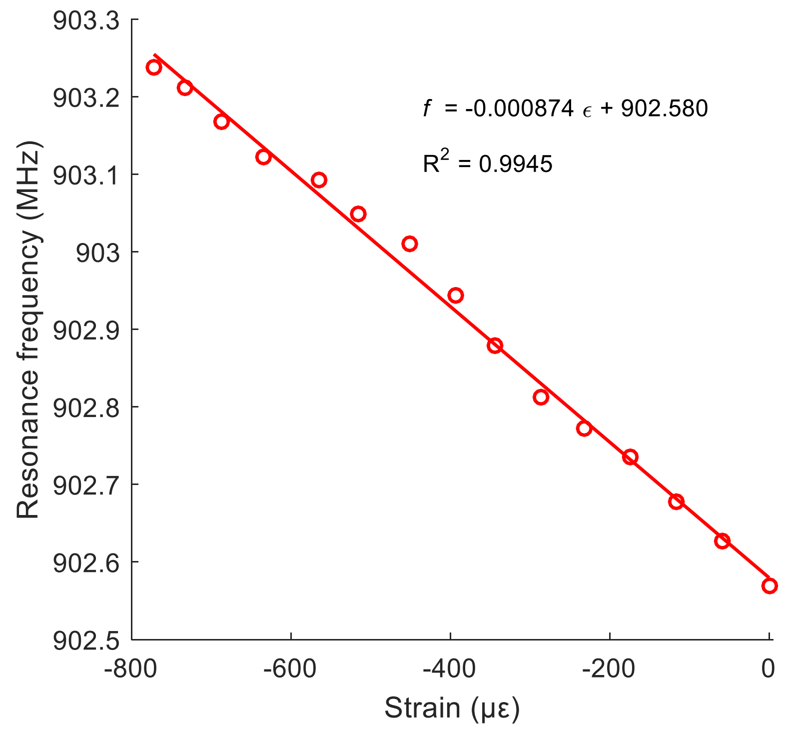
Compression Test Results

- At each strain level, sweep frequency band to get transmitted power curve.
- From transmitted power curve, the resonance frequency is extracted.

Transmitted power



Resonance frequency-strain curve

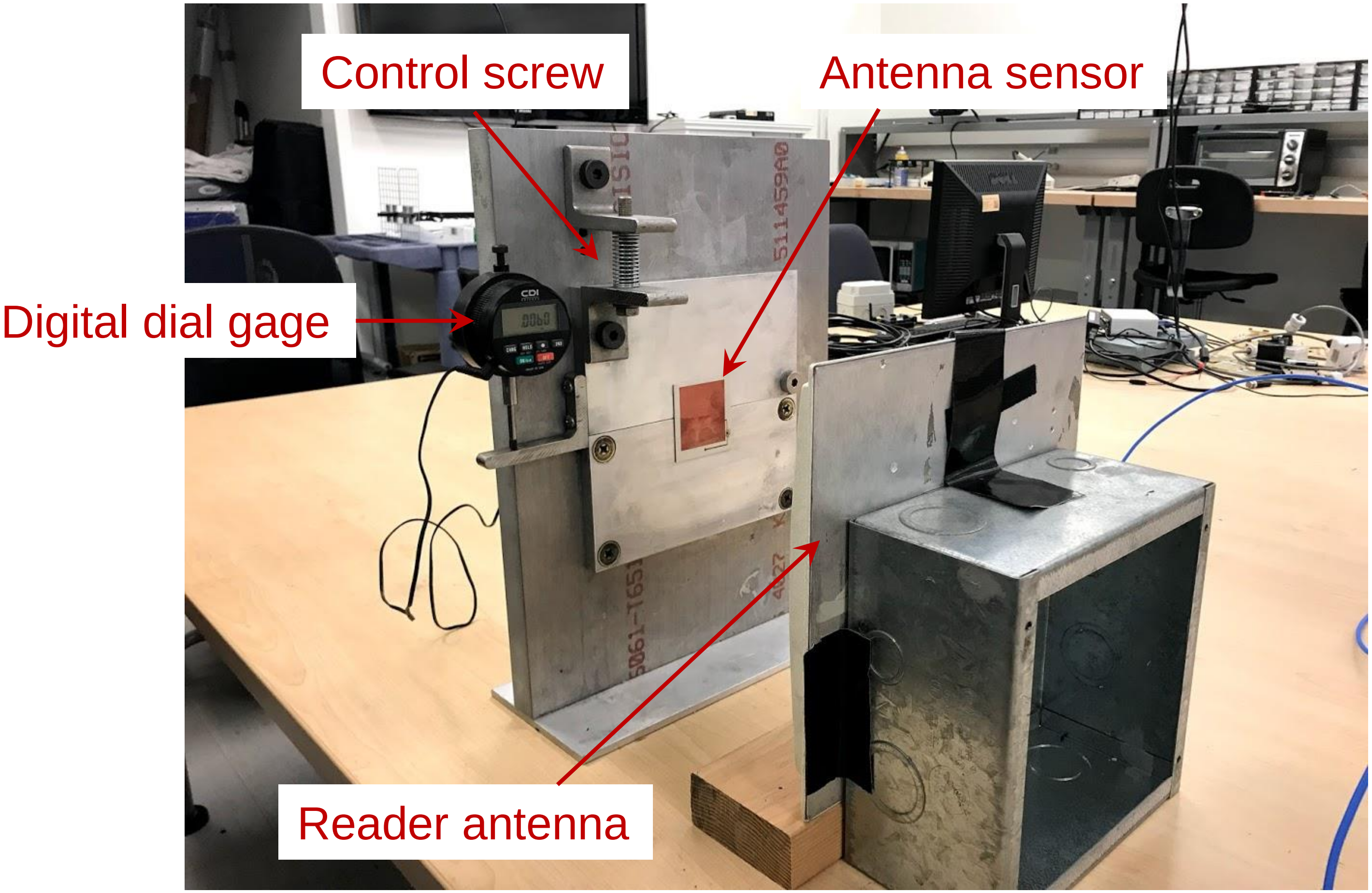


Outline

- ❑ Research Background & Motivation
- ❑ Thermal Stability Tests
- ❑ Material Property Tests
  - ➢ Constitutive Relationship of Substrate
  - ➢ Constitutive Relationship of Glue
  - ➢ Dielectric Constant of Substrate
- ❑ Multi-Physics Simulation
- ❑ Validation Tests
  - ➢ Strain Sensing Test
  - ➢ Crack Sensing Test
- ❑ Conclusion

Crack Test

Experiment setup



Crack Propagation

2 mils

6 mils

10 mils

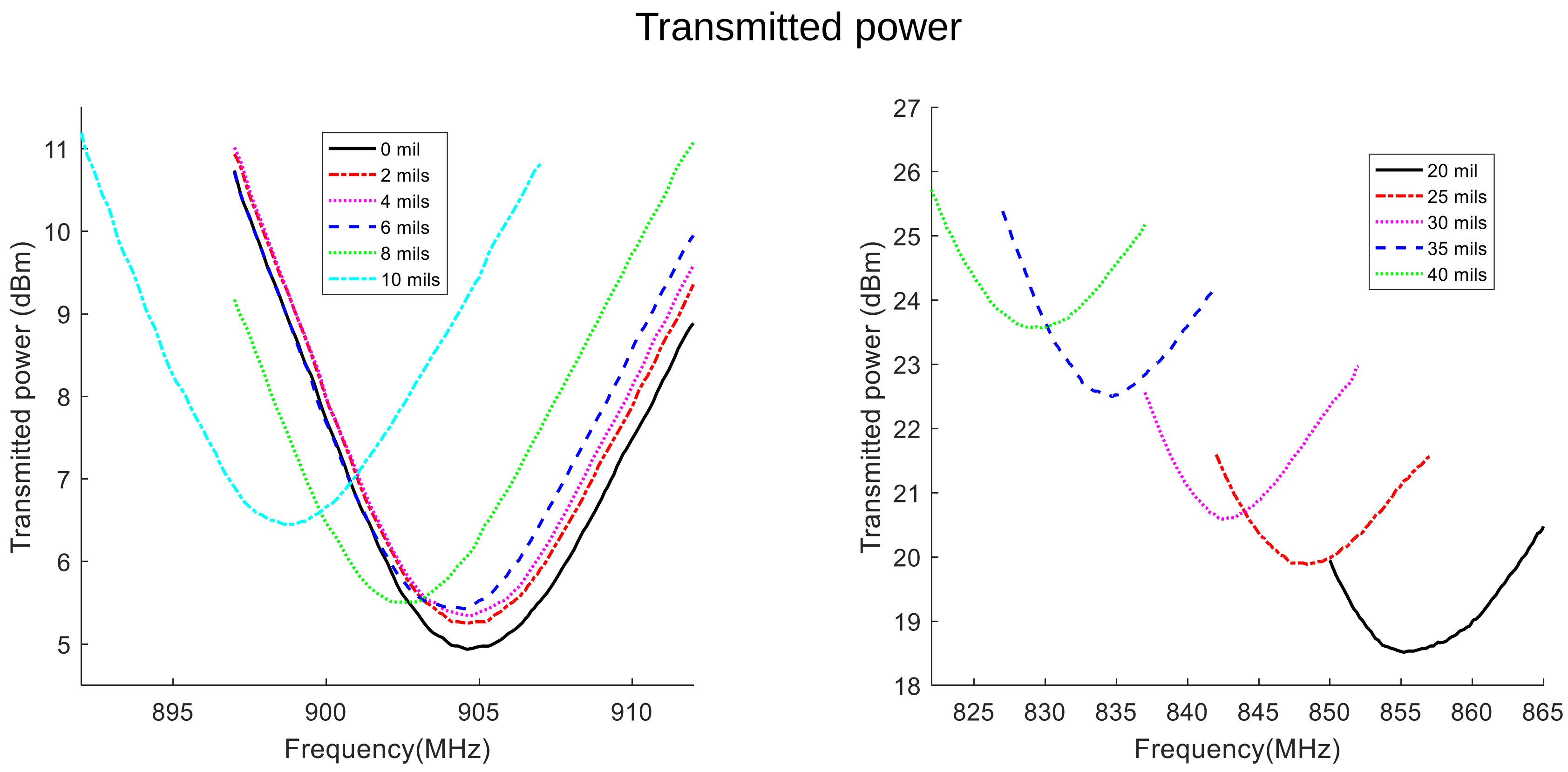
20 mils

30 mils

40 mils

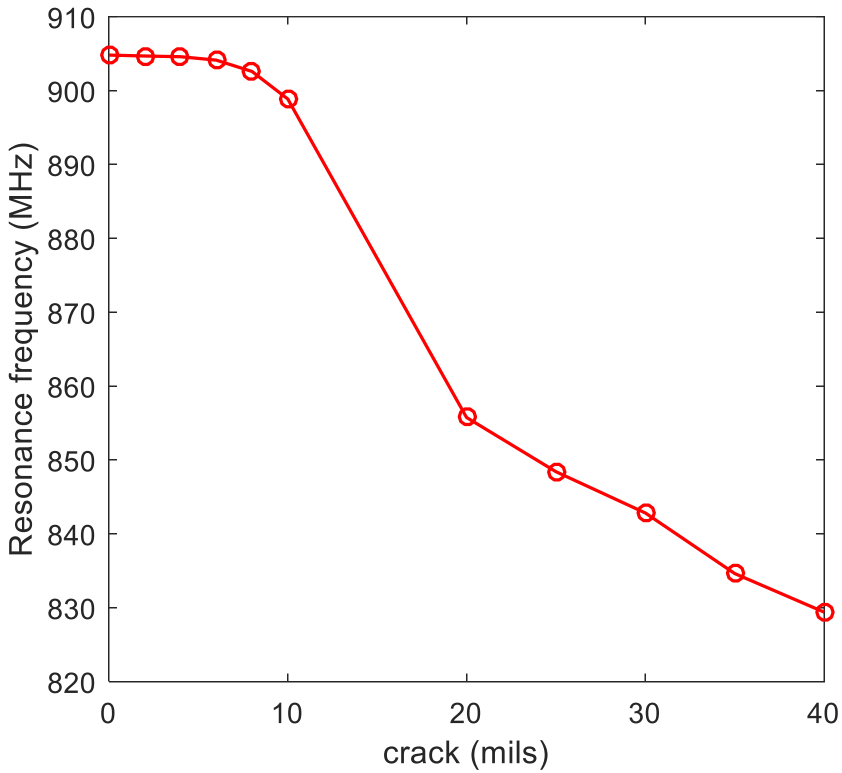
Crack Test Results

At each crack level, sweep frequency band to get transmitted power curve.



Crack Rest Results

- From transmitted power curve, resonance frequency is extracted.
- The resonance frequency decreases as crack propagates along sensor’s width direction.



Conclusions

1. The sensor with RT/duroid® 6202 substrate is shown to be more stable under temperature disturbance compared with previous sensor with substrate material RT/duroid® 5880.

2. Multi-physics simulation can accurately model behaviors of the antenna sensor. Incorporating nonlinear constitutive properties in the model can improve the accuracy of the simulation results on strain sensitivity.

3. The antenna sensor is capable of estimating small strain changes on structures. The resonance frequency of the antenna sensor increases as the compression strain is applied.

4. The antenna sensor can monitor surface crack growth. As crack propagates, the resonance frequency of the antenna sensor reduces as expected.

Acknowledgements

INSPIRE University Transportation Center
through USDOT/OST-R grant #69A3551747126

INSPIRE
UNIVERSITY TRANSPORTATION CENTER
LED BY MISSOURI S&T

Thank You

Questions and Comments?